CLAIMS

1. A method of manufacturing an IC chip packaged device in which

a film substrate that has antenna circuits formed at a fixed spacing on one surface thereof is transported at a constant speed, and

IC chips are moved along the film substrate, and are mounted at the fixed spacing on the film substrate so as to be connected to the antenna circuits.

2. The method of manufacturing an IC chip packaged device according to claim 1, wherein an image of the IC chip is picked up, a correction amount for correcting the position where the IC chip is to be mounted is then calculated from the picked up image, and the position where the IC chip is to be mounted is then corrected.

3. An apparatus for manufacturing an IC chip packaged device comprising:

a transporting section that transports a film substrate that has antenna circuits formed at a fixed spacing on one surface thereof at a constant speed; and

an IC chip mounting section that mounts IC chips on the film substrate,

wherein the IC chip mounting section is provided with: a synchronized roller section that, while moving the IC chips along the film substrate, mounts the IC chips at the fixed spacing on the film substrate that is being transported at the constant speed; and an IC chip supply section that supplies the IC chips to the synchronized roller section.

4. The apparatus for manufacturing an IC chip packaged device according to claim 3, wherein the IC chip mounting section is provided with a plurality of the synchronized roller sections.

5. The apparatus for manufacturing an IC chip packaged device according to claim 4, wherein, of the plurality of synchronized roller sections, at least one is a dedicated backup synchronized roller section that mounts an IC chip on the antenna circuit where an IC chip has not been mounted by the other synchronized roller sections.

6. An apparatus for manufacturing an IC chip packaged device comprising:

a transporting section that transports a film substrate; and

an IC chip mounting section that mounts IC chips on the film substrate,

wherein the transporting section has a surface supporting section that supports on its surface the film substrate from a position in front of a mounting position where the IC chip is mounted by the IC chip mounting section to a position behind the mounting position, and

the IC chip mounting section has a synchronized roller section that, while moving the IC chips at the same speed as the film substrate, mounts the IC chips on the film substrate, and an IC chip supply section that supplies the IC chips to the synchronized roller section.

7. The apparatus for manufacturing an IC chip packaged device according to claim 6, wherein the surface supporting section has a suction mechanism that suctions the film substrate.

8. An apparatus for manufacturing an IC chip packaged device comprising:

a transporting section that transports a film substrate; and

an IC chip mounting section that mounts IC chips on the film substrate,

wherein the IC chip mounting section has a synchronized roller section that, while moving the IC chips at the same speed as the film substrate, mounts the IC chips on the film substrate, and an IC chip supply section that supplies the IC chips to the synchronized roller section, and

the synchronized roller section is provided with a roller that axially rotates around an axis of rotation and mounts the IC chips on the film substrate, and protruding portions that hold the IC chips at a distal end portion are formed on a circumferential surface of the roller.